Abstract

Provided is an inspection method for inspecting an inspection object of a first substrate, comprising: (a) preparing the first substrate having a first electrode connected to the inspection object; (b) preparing a second substrate having a second electrode and a bonding portion which are formed on a first main surface, and having a third electrode formed on a second main surface opposite to the first main surface and electrically connected to the second electrode; (c) bringing the first electrode and the second electrode into electrical contact with each other and forming a sealed space between the first substrate and the second substrate by bonding the first substrate and the second substrate with an adhesive interposed therebetween; (d) curing the adhesive; (e) inspecting the inspection object; and (f) separating the first substrate from the second substrate.